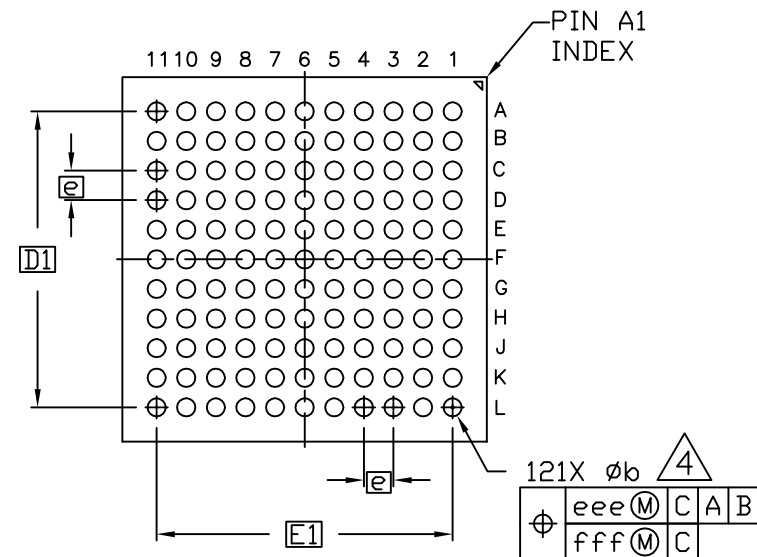
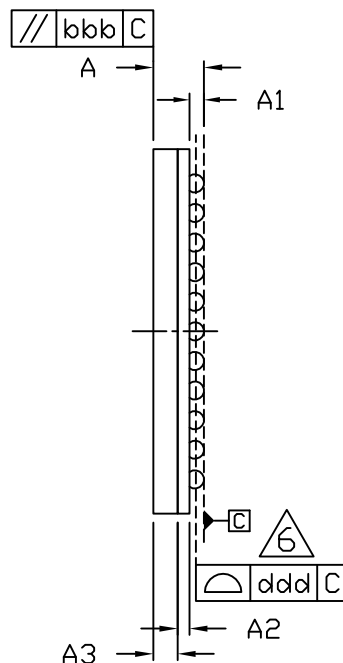
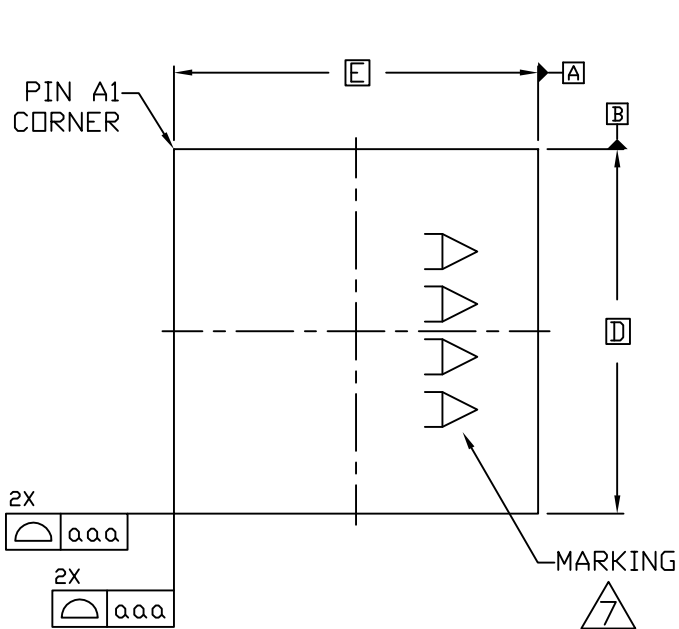




NOTES:

1. DIMENSIONS ARE IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.
2. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
3. SYMBOL 'N' IS THE NUMBER OF BALLS AFTER DEPOPULATING.
4. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM $\square$
5. THE BASIC SOLDER BALL DIA IS 0.400 MM.
6. PRIMARY DATUM $\square$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
7. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
8. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE.
9. PACKAGE CODE: X12188+1

DIMENSION	MIN.	NOM.	MAX.
A	1.010	1.110	1.210
A1	0.270	-	0.370
A2	0.260 REF.		
A3	0.530 REF.		
b	0.380	-	0.480
D	8.000 BSC		
D1	6.500 BSC		
E	8.000 BSC		
E1	6.500 BSC		
e	0.650 BSC		
aaa	0.150		
bbb	0.200		
ddd	0.120		
eee	0.150		
fff	0.080		
N	121		

MAXIM

TITLE:

PACKAGE OUTLINE, 121 BALLS CTBGA,
8x8x1.1mm, 0.65mm PITCH

APPROVAL

DOCUMENT CONTROL NO.

21-0680

REV.

A

1/1

-DRAWING NOT TO SCALE-